



Click [here](#) for the 3D model.

| Dimensions | |
|------------|---------------------|
| D | 6.3mm +/-0.5mm |
| L | 7.7mm +/-0.3mm |
| W | 0.65mm +/-0.1mm |
| F | 0.3mm MAX |
| A | 6.6mm +/-0.2mm |
| B | 6.6mm +/-0.2mm |
| C | 7.8mm MAX |
| E | 2.6mm +/-0.2mm |
| G | 0.35mm +0.15/-0.2mm |
| P | 1.8mm +/-0.2mm |

Packaging Specifications

Packaging T&R

| General Information | |
|---------------------|--------------------------------------|
| Series | EDT |
| Dielectric | Aluminum Electrolytic |
| Style | SMD Can |
| Description | Surface Mount, Aluminum Electrolytic |
| RoHS | Yes |
| Lead | V-Chip |
| Qualifications | AEC-Q200 |
| AEC-Q200 | Yes |

| Specifications | |
|-------------------------|------------------------|
| Capacitance | 47 uF |
| Capacitance Tolerance | 20% |
| Voltage DC | 25 VDC, 32 VDC (Surge) |
| Temperature Range | -40/+125°C |
| Rated Temperature | 125°C |
| Life | 1000 Hrs |
| Dissipation Factor | 18% |
| Ripple Current | 70 mAmps (120Hz 125C) |
| Leakage Current | 11.8 uA (2min 20°C) |
| Impedance Ratio at -25C | 2 |
| Impedance Ratio at -40C | 3 |
| High Temperature Solder | true |